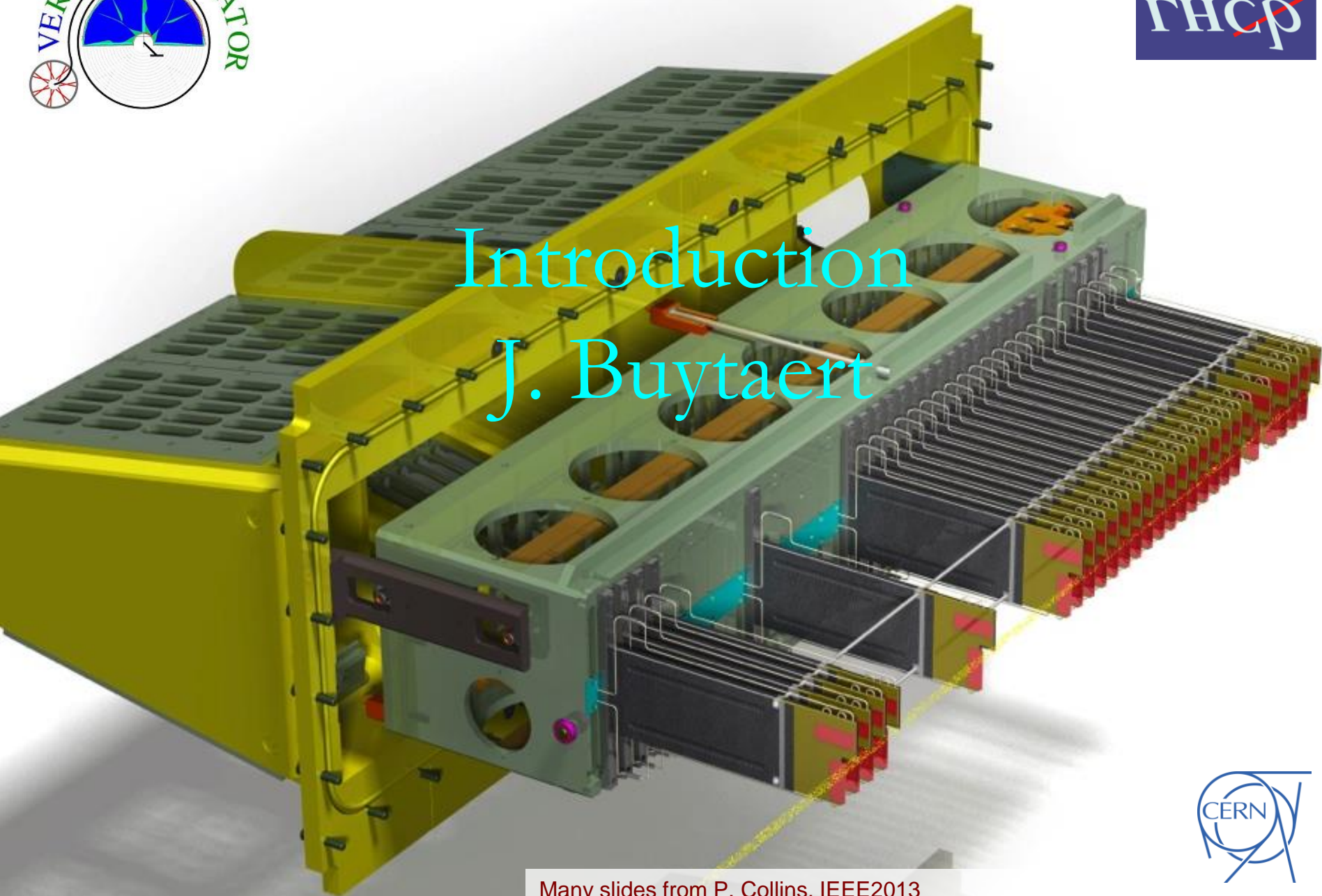




Introduction

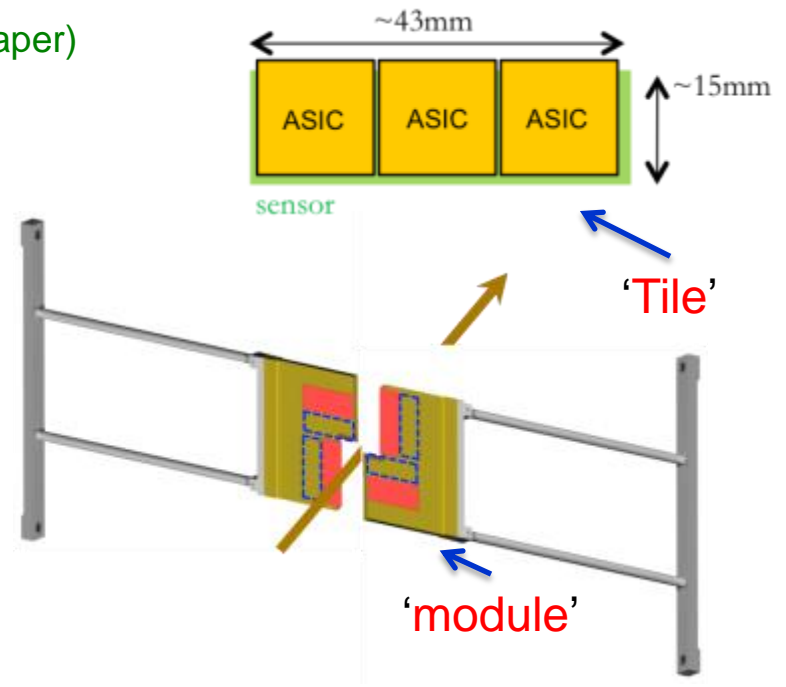
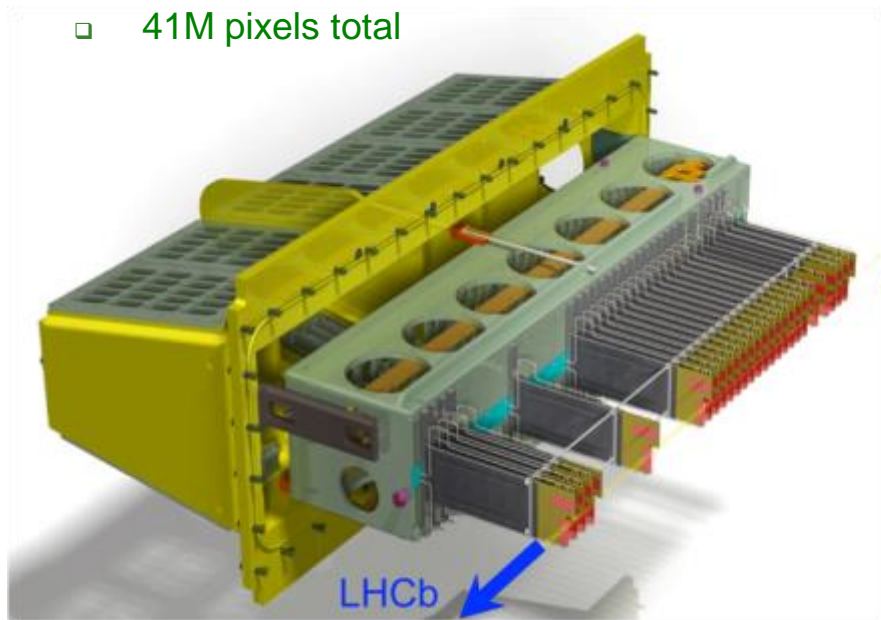
J. Buytaert



Upgraded VELO (VErteX LOcator)

Function of VELO remains: provide precise tracking and trigger on displaced vertices
Conditions more challenging: increased occupancies, data rates and radiation damage

- Choice for pixels vs strips was made on 17th July 2013
- L shape **modules** face each other to form **stations**
- 4 sensor **tiles** per module. Each sensor has 3 ASICs with $55 \times 55 \mu\text{m}^2$ pixels
- 26 stations arranged perpendicularly along beam direction
 - total active area 1237 cm^2 (= size of A3 sheet of paper)
 - 41M pixels total



Challenges for upgraded VELO

Sensor Radiation Damage

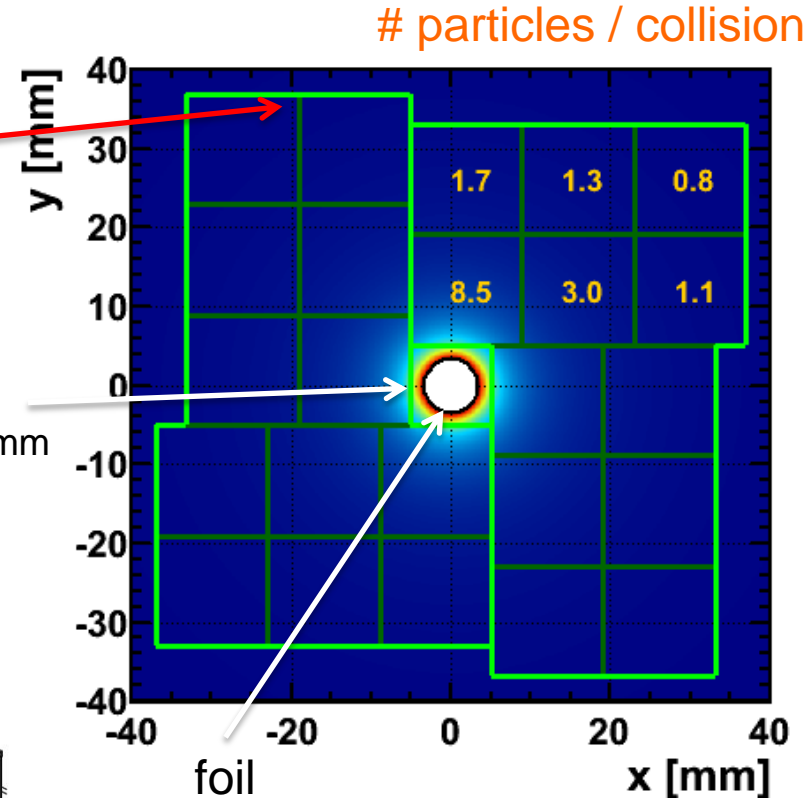
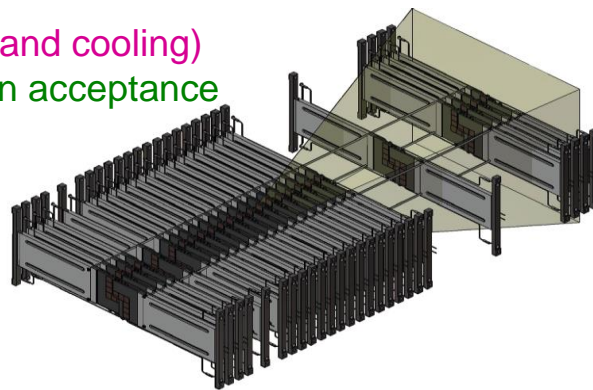
- Highly non-uniform radiation damage of up to 8×10^{15} n_{eq}/cm^2 for 50 fb^{-1} (= full lifetime super LHC)
- Factor 40 less at sensor outer corner
- Expect up to 7nA per pixel and 130 mW per tile
- ASICS must tolerate 400 MRad

Enormous Data Rates

- ~8.5 tracks/collision for hottest ASIC
- Hottest chip 230-320 Mtrack/s
- 600-900 Mhits/s/ chip
- Data volume of whole VELO: **2.5 Tbit/s**

Material Budget (thinning and cooling)

- Modules are partially in acceptance
- Thin foil essential



Pixel module layout superposed above anticipated flux (arbitrary scale)

Micro-channel cooling

The challenge:

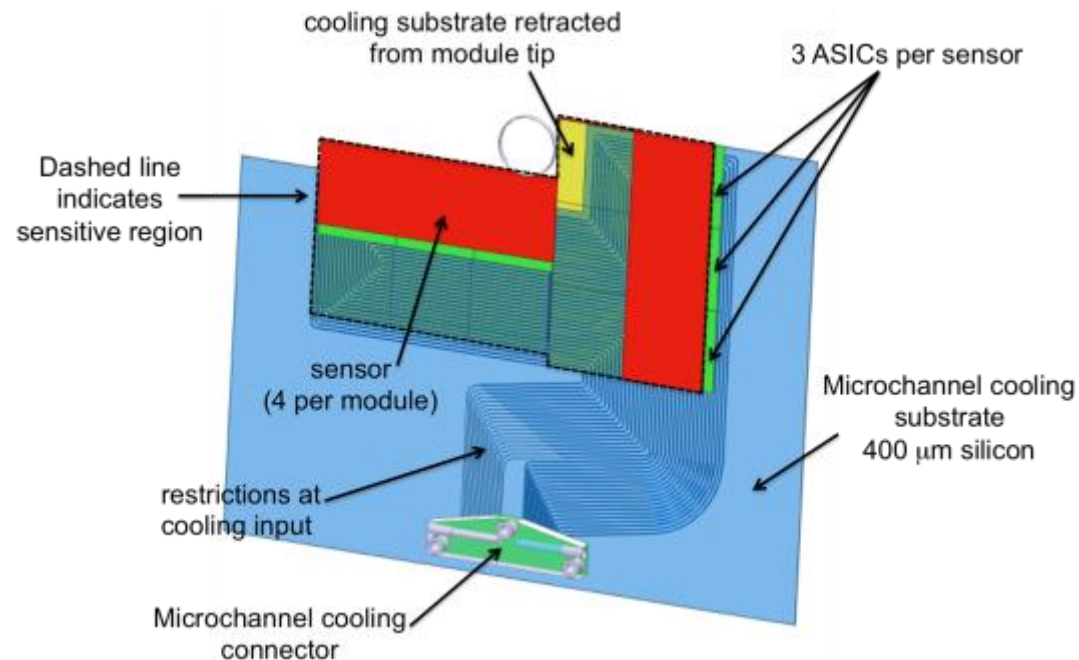
High speed pixel readout chips produce a lot of heat ($\sim 1.5 \text{ W/cm}^2$)

Necessary to keep the sensors at $< -20 \text{ }^\circ\text{C}$ to minimize the effects of radiation damage, and to avoid thermal runaway

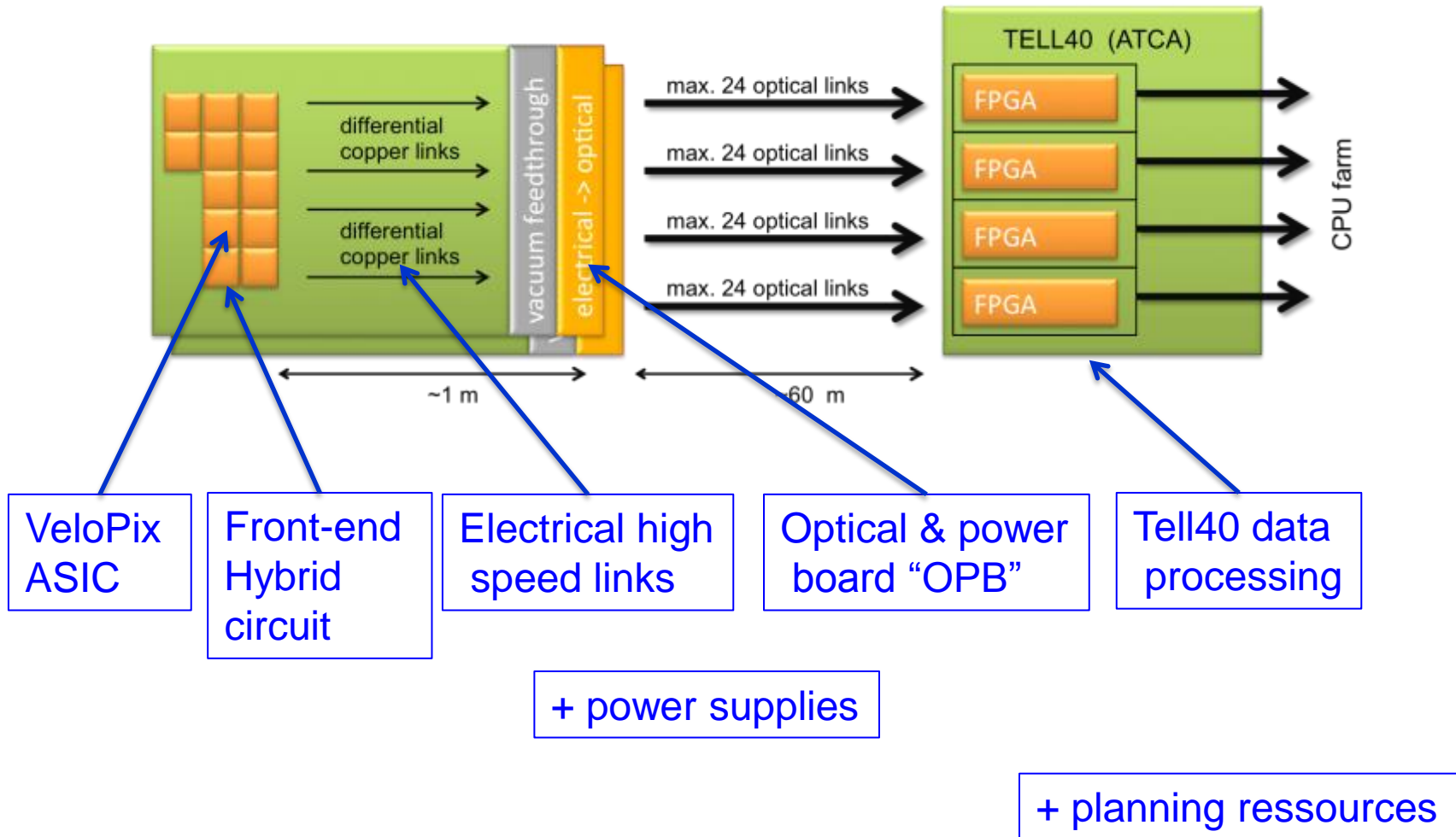
Should avoid material, especially at the tip of the module (where radiation damage is highest)

Novel solution: evaporate CO_2 via micro-channels etched in Si substrate

- High heat transfer coefficients
- no CTE difference (Si on Si)
- excellent uniformity of material in sensitive region
- Method developed with CERN PH-DT group
- Pressure tolerance of module very important



Electronics review topics



Some remarks

- Progress in the various areas is very different:
 - Design is quite well advanced for
 - 'VeloPix'
 - 'Electrical high speed links'.
 - At conceptual stage for
 - 'front-end hybrid',
 - 'Optical & power board'
 - 'Tell40 Data processing'
- Velopix ASIC is not 'fully' part of this review
 - Review only its interface with the rest of the system:
 - Data in/outputs, Fast & slow control, powering, ...
 - Not 'Internally' : very complex ASIC and requires a separate review (early 2014 ?)
 - Nevertheless , an extensive presentation is provided for full understanding of the system.
- Documentation:
 - We benefit somewhat from the writing of the Technical Design Report...